

**Features:**

- Isolated mounting base 4000V~
- Pressure contact technology with Increased power cycling capability
- Space and weight saving

Typical Applications

- Various rectifiers
- DC supply for PWM inverter

V _{RRM}	Type & Outline
	MDx800-38-412F3
3800V	MDx800-40-412F3
4000V	MDx800-42-412F3
4200V	MDx800-44-412F3
4400V	MDx800-44-412F3

MDx stands for any type of MDC, MDA, MDK

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T _J (°C)	VALUE			UNIT
				Min	Type	Max	
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled,T _c =85°C	150			800	A
I _{F(AV)}	Mean forward current	180° half sine wave 50Hz Single side cooled,T _c =100°C				665	A
I _{F(RMS)}	RMS forward current	180° half sine wave 50Hz Single side cooled,T _c =85°C	150			1256	A
I _{RRM}	Repetitive peak current	at V _{RRM}	150			100	mA
I _{FSM}	Surge forward current	10ms half sine wave V _R =60%V _{RRM}	150			23.0	kA
I ² t	I ² t for fusing coordination					2645	10 ³ A ² s
V _{FO}	Threshold voltage		150			0.90	V
r _F	Forward slope resistance					0.36	mΩ
V _{FM}	Peak forward voltage	I _{FM} =2400A	25			1.75	V
R _{th(j-c)}	Thermal resistance Junction to case	Single side cooled per chip				0.050	°C /W
R _{th(c-h)}	Thermal resistance case to heatsink	Single side cooled per chip				0.016	°C /W
V _{iso}	Isolation voltage	50Hz,R.M.S,t=1min,I _{iso} :1mA(MAX)		4000			V
F _m	Terminal connection torque(M12)					14.0	N·m
	Mounting torque(M8)					12.0	N·m
T _{vj}	Junction temperature			-40		150	°C
T _{stg}	Stored temperature			-40		125	°C
W _t	Weight				3660		g
Outline				412F3			

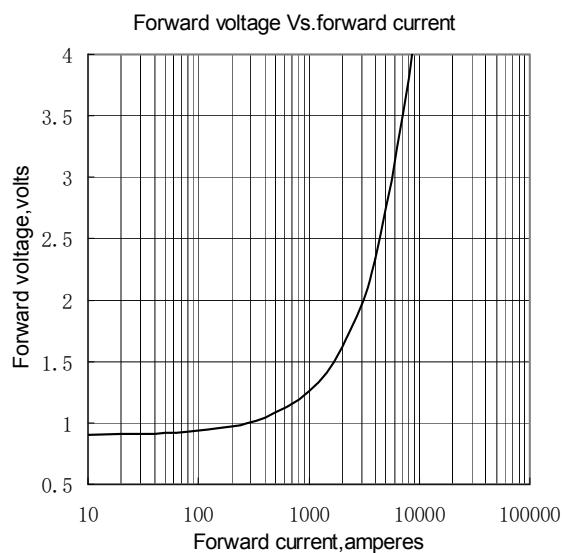


Fig1

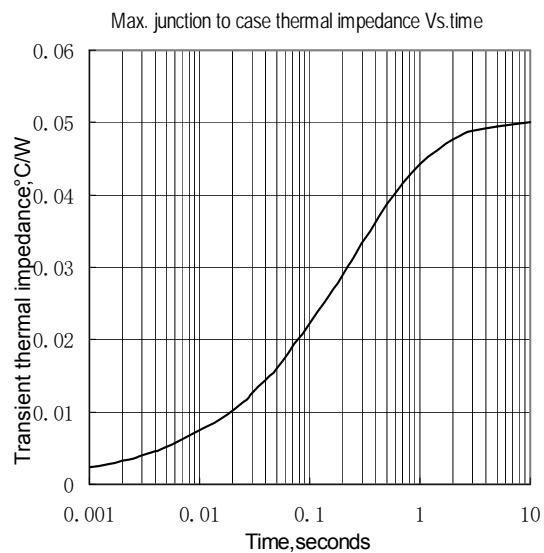


Fig2

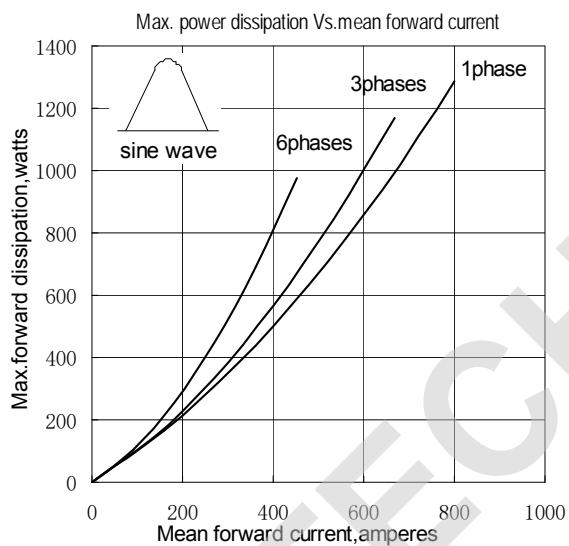


Fig3

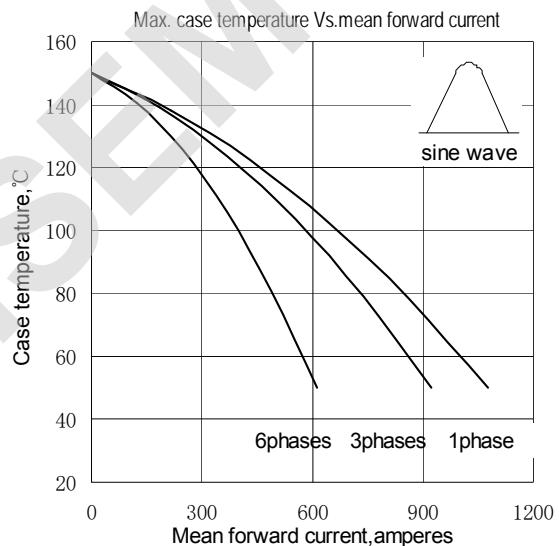


Fig4

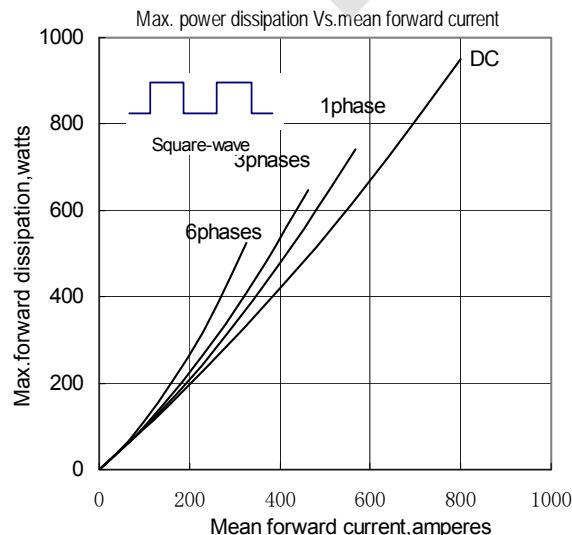


Fig5

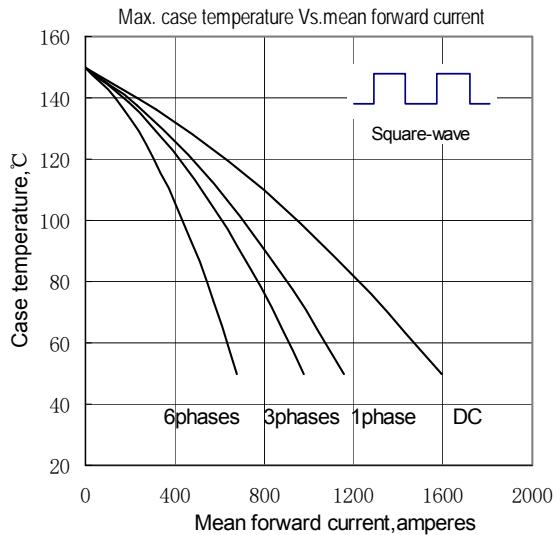


Fig6

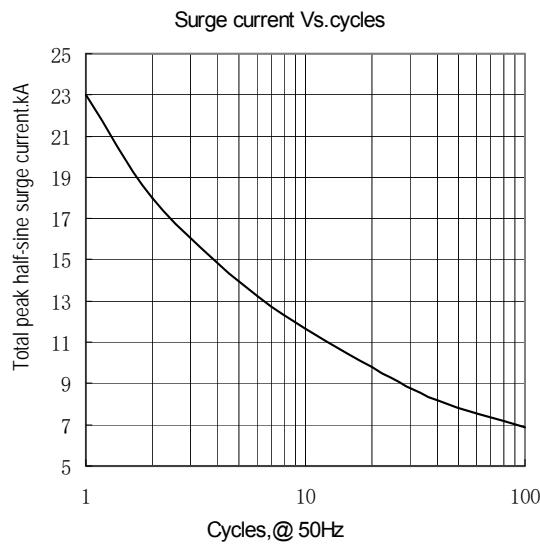


Fig7

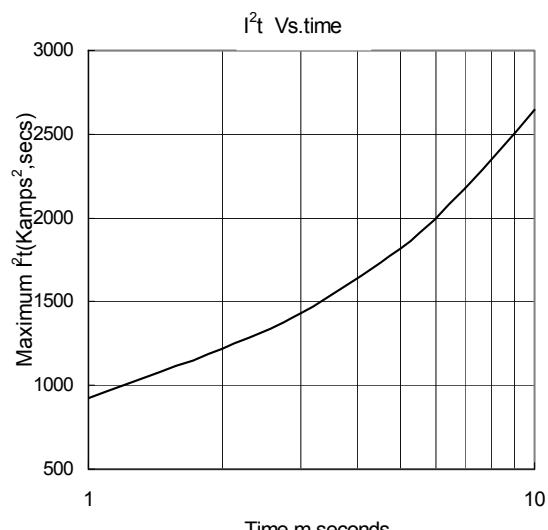
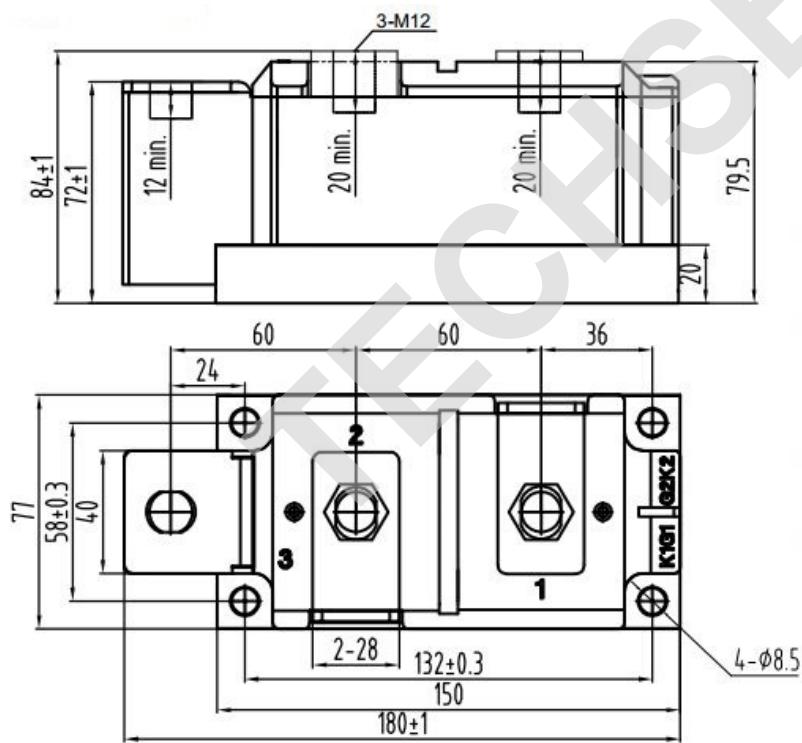


Fig8

Outline:Unmarked dimensional tolerance: $\pm 0.5\text{mm}$

TECHSEM reserves the right to change specifications without notice.

